E2 Technical Specifications

Raise3D E2 is a desktop 3D printer with independent dual extruders (also known as IDEX). IDEX gives Raise3D E2 the ability to perform more advanced functions, such as Mirror Mode and Duplication Mode, making this printer ideal for professional 3D printing. Its unique extruder gear design enables it to use flexible 3D printing materials, such as TPU, more reliably and with better results.

Printer	Raise3D E2			
Build Volume (W × D × H)	Single Extruder Print		Dual Extruder Print	
	330 × 240 × 240 mm (13 × 9.4 × 9.4 inch)		295 × 240 × 240 mm (11.6 × 9.4 × 9.4 inch)	
Machine Size	607 × 596 × 465 mm (23.9 × 23.5 × 18.3 inch)			
Weight	Net Weight	Gross Wei	ght (Carton Only)	Gross Weight (Carton with Pallet)
	35.1 kg (77.4 lbs)	43.8 kg (96.6 lbs)		51.3 kg (113.1 lbs)
Electrical	Power Supply Input Power Supply Output	100-240 V AC, 50/ 60 Hz 230 V @ 2 A 24 V DC, 350 W		
General	Print Technology Print Head System Filament Diameter XYZ Step Size Print Head Travel Speed Build Plate Max Build Plate Temperature Heated Bed Material Build Plate Leveling Filament Run-out Sensor Layer Height Nozzle Diameter Hot End Max Nozzle Temperature Connectivity Noise Emission (Acoustic) Operating Ambient Temperature Storage Temperature Filter Technical Certifications	Fused Filament Fabrication (FFF) IDEX Independent Dual Extruders 1.75 mm 0.78125, 0.78125, 0.078125 micron 15-150 mm/s Flexible Steel Plate with BuildTak 110°C Silicone Mesh-leveling with Flatness Detection Available The E2 is compatible with 0.2, 0.4, 0.6, 0.8 and 1.0 mm nozzles, and the layer height can vary between 0.1-0.5 mm. To achieve stable print results, when using 0.4 mm nozzles, we recommend using a layer height between 0.1-0.3 mm. 0.4 mm (Default), 0.6/ 0.8 mm (Available) V3P 300°C Wi-Fi, LAN, USB Port, Live Camera < 50 dB (A) When Building 15-30°C, 10-90% RH, non-condensing -25°C to +55°C, 10-90% RH, non-condensing HEPA Filter with Activated Charcoal CB, CE, FCC, RoHS, RCM		
Material	Material Type Third Party Material	PLA/ ABS/ ASA/ PETG/ PC/ PETG ESD/ TPU 95A/ PVA+ Supported by Raise3D OFP (Open Filament Program)*		
Software	Slicing Software Supported File Types Supported OS Machine Code Type	ideaMaker STL/ OBJ/ 3MF/ OLTP Windows/ macOS/ Linux GCODE		
Printer Controller	User Interface Network Power Loss Recovery Screen Resolution Motion Controller Logic Controller Memory Onboard Flash OS Ports	7-inch Touch Screen Wi-Fi, Ethernet Available 1024 × 600 Atmel ARM Cortex-M4 120 MHz FPU NXP ARM Cortex-A9 Quad 1 GHz 1 GB 16 GB Embedded Linux USB 2.0 × 2, Ethernet × 1		

^{*}For detailed information and slicing profiles of the materials supported by Raise3D OFP, please visit https://www.ideamaker.io/.

